



Material Composition Declaration

EPC2069

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/13/2021
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	15.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	12.2338	80.8928	83.8022	808928
	Silicon oxide	7631-86-9	0.0619	0.4091		4091
	Silicon nitride	12033-89-5	0.0183	0.1209		1209
	Gallium nitride	25617-97-4	0.0782	0.5169		5169
	Aluminum	7429-90-5	0.1278	0.8451		8451
	Aluminum nitride	24304-00-5	0.0189	0.1247		1247
	Titanium	7440-32-6	0.0042	0.0275		275
	Titanium nitride	25583-20-4	0.0153	0.1009		1009
	Copper	7440-50-8	0.0021	0.0141		141
	Tungsten	7440-33-7	0.0063	0.0417		417
	Polyimide		0.1071	0.7085		7085
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0110	0.1202	110
	Copper	7440-50-8	0.0165	0.1092		1092
Solder Bump	Copper	7440-50-8	0.1652	1.0921	16.0776	10921
	Nickel	7440-02-0	0.0985	0.6515		6515
	Tin	7440-31-5	2.1288	14.0760		140760
	Silver	7440-22-4	0.0390	0.2580		2580
Sum in total:			15.1235	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.